IN THE CLAIMS:

This listing of clams will replace all prior versions, and listings, of claims in the application:

1-5. (canceled).

6. (currently amended) A method of manufacturing a self-light-emitting device, comprising the steps of:

filling a nozzle with an application liquid comprising an organic light-emitting material for forming an EL layer; and

~~continuously~~ discharging said application liquid comprising said organic light-emitting material to a pixel column by ultrasonic oscillations while the nozzle and the pixel column are connected through the application liquid comprising said organic light-emittng material.

7. (original) A method of manufacturing a self-light-emitting device according to claim 6, wherein:

said nozzle has a large internal diameter portion and a small internal diameter portion;

said small internal diameter portion has a heater; and

said heater applies heat to the application liquid filling the nozzle.

8-9. (canceled)

10. (previously presented) A method of manufacturing a self-light-emitting device

according to claim 6, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

11. (previously presented) A method of manufacturing a self-light-emitting device according to claim 6, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid and a pressure, and is applied.

12. (previously presented) A method of manufacturing a self-light-emitting device according to claim 19, wherein said application liquid filling said nozzle is applied by bringing a contact element of said nozzle into contact with said bank.

13-18. (canceled)

19. (previously presented) A method of manufacturing a light-emitting device according to claim 6, wherein said self-light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

20. (currently amended) A method of manufacturing a light-emitting device comprising:

filling a nozzle with an application liquid comprising an organic light-emitting material for forming an EL layer; and

~~continuously~~ discharging said application liquid comprising said organic light-emitting

material to a pixel column by ultrasonic oscillations and heat while the nozzle and the pixel column are connected through the application liquid comprising said organic light-emittng material.

21. (previously presnted) A method of manufacturing a light-emitting device according to claim 20, wherein said nozzle has a large internal diameter portion and a small internal diameter portion, said small internal diameter portion has a heater, and said heater applies heat to the application liquid filling the nozzle.

22. (previously presented) A method of manufacturing a light-emitting device according to claim 20, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

23. (previously presented) A method of manufacturing a light-emitting device according to claim 20, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid, and a pressure, and is applied.

24. (previously presented) A method of manufacturing a light-emitting device according to claim 20, wherein said light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

25. (previously presented) A method of manufacturing a light-emitting device according to

claim 24, wherein said application liquid filling said nozzle is applied by bringing a contact element of said nozzle into contact with said bank.

26. (currently amended) A method of manufacturing a light-emitting device comprising:

forming [a] at least first and second thin film ~~transistor~~ transistors over a substrate;

forming an insulating film over said at least first and second thin film ~~transistor~~ transistors;

forming [a] at least first and second pixel ~~electrode~~ electrodes over said insulating film;

forming a bank covering at least an edge portion of said first pixel electrode and an edge portion of the second pixel electrode over said insulating film;

filling a nozzle with an application liquid comprising ~~an organic~~ a light-emitting material for forming an EL layer; and

~~continuously~~ discharging said application liquid comprising said ~~organic~~ light-emitting material to ~~a pixel column~~ the first and second pixel electrodes so that the EL layer has a stripe shape over the first and second pixel electrodes by ultrasonic oscillations while the nozzle and the ~~pixel column~~ first and second pixel electrodes are connected through the application liquid comprising said ~~organic~~ light-emitting material,

wherein the first and second pixel electrodes are electrically connected to the first and second thin film transistors respectively, and

wherein the light-emitting material comprises an organic material.

27. (previously presented) A method of manufacturing a light-emitting device according to claim 26, wherein said nozzle has a large internal diameter portion and a small internal diameter

portion, said small internal diameter portion has a heater, and said heater applies heat to the application liquid filling the nozzle.

28. (previously presented) A method of manufacturing a light-emitting device according to claim 26, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

29. (previously presented) A method of manufacturing a light-emitting device according to claim 26, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid, and a pressure, and is applied.

30. (previously presented) A method of manufacturing a light-emitting device according to claim 26, wherein said application liquid filling said nozzle is applied by bringing a contact element of said nozzle into contact with said bank.

31. (currently amended) A method of manufacturing a self-light-emitting device, comprising the steps of:

filling a nozzle with an application liquid comprising an organic light-emitting material for forming an EL layer; and

~~continuously~~ discharging said application liquid comprising said organic light-emitting material to a pixel column by ultrasonic oscillations with scanning the nozzle along a direction

parallel to the pixel column while the nozzle and the pixel column are connected through the application liquid comprising said organic light-emittng material.

32. (previously presented) A method of manufacturing a self-light-emitting device according to claim 31, wherein:

said nozzle has a large internal diameter portion and a small internal diameter portion;

said small internal diameter portion has a heater; and

said heater applies heat to the application liquid filling the nozzle.

33. (previously presented) A method of manufacturing a self-light-emitting device according to claim 31, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

34. (previously presented) A method of manufacturing a self-light-emitting device according to claim 31, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid and a pressure, and is applied.

35. (previously presented) A method of manufacturing a self-light-emitting device according to claim 36, wherein said application liquid filling said nozzle is applied by bringing a contact element of said nozzle into contact with said bank.

36. (previously presented) A method of manufacturing a light-emitting device according to claim 31, wherein said self-light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

37. (currently amended) A method of manufacturing a light-emitting device comprising:

filling a nozzle with an application liquid comprising an organic light-emitting material for forming an EL layer; and

~~continuously~~ discharging said application liquid comprising said organic light-emitting material to a pixel column by ultrasonic oscillations and heat with scanning the nozzle along a direction parallel to the pixel column while the nozzle and the pixel column are connected through the application liquid comprising said organic light-emittng material.

38. (previously presented) A method of manufacturing a light-emitting device according to claim 37, wherein said nozzle has a large internal diameter portion and a small internal diameter portion, said small internal diameter portion has a heater, and said heater applies heat to the application liquid filling the nozzle.

39. (previously presented) A method of manufacturing a light-emitting device according to claim 37, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

40. (previously presented) A method of manufacturing a light-emitting device according to

claim 37, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid, and a pressure, and is applied.

41. (previously presented) A method of manufacturing a light-emitting device according to claim 37, wherein said light-emitting device comprises a pixel electrode over a substrate and a bank covering at least an edge portion of said pixel electrode over said substrate.

42. (previously presented) A method of manufacturing a light-emitting device according to claim 41, wherein said application liquid filling said nozzle is applied by bringing a contact element of said nozzle into contact with said bank.

43. (currently amended) A method of manufacturing a light-emitting device comprising:

forming [a] at least first and second thin film ~~transistor~~ transistors over a substrate;

forming an insulating film over said at least first and second thin film ~~transistor~~ transistors;

forming [a] at least first and second pixel ~~electrode~~ electrodes over said insulating film;

forming a bank covering at least an edge portion of said first pixel electrode and an edge portion of the second pixel electrode over said insulating film;

filling a nozzle with an application liquid comprising ~~an organic~~ a light-emitting material for forming an EL layer; and

~~continuously~~ discharging said application liquid comprising said ~~organic~~ light-emitting material to ~~a pixel column~~ the first and second pixel electrodes so that the EL layer has a stripe shape

over the first and second pixel electrodes by ultrasonic oscillations with scanning the nozzle along a direction parallel to the ~~pixel column~~ bank while the nozzle and the ~~pixel column~~ first and second pixel electrodes are connected through the application liquid comprising said ~~organic~~ light-emitting material,

wherein the first and second pixel electrodes are electrically connected to the first and second thin film transistors respectively, and

wherein the light-emitting material comprises an organic material.

44. (previously presented) A method of manufacturing a light-emitting device according to claim 43, wherein said nozzle has a large internal diameter portion and a small internal diameter portion, said small internal diameter portion has a heater, and said heater applies heat to the application liquid filling the nozzle.

45. (previously presented) A method of manufacturing a light-emitting device according to claim 43, wherein said application liquid is pushed out from said nozzle by pressurization, and is applied.

46. (previously presented) A method of manufacturing a light-emitting device according to claim 43, wherein said application liquid is pushed out from said nozzle by a medium selected from a group consisting of capillary action, a weight of said application liquid, and a pressure, and is applied.

47. (previously presented) A method of manufacturing a light-emitting device according to claim 43, wherein said application liquid filling said nozzle is applied by contacting a contact element of said nozzle with said bank.